IPE	
FORM PTO-1595 U.S. DEPARTMENT OF COMMERCE 07 - 06 - 2005 1-31-92 UN 2 1 200 REC	
To the Honorable Commissioner of Parents and Trade	s or copy thereof. solving party(ies):
1. Name of conveying party(res).	Aving party(les):
Kenji Nakano	
Additional name(s) of conveying party(ies) attached? YesX No	Name: Sony Corporation Internal Address:
3. Nature of Conveyance:	Street Address: 7-35 Kitashinagawa 6-chome,
X Assignment Merger	Shinagawa-ku, Tokyo, 141-0032 JAPAN
Security Agreement Change of Name	
Other	City State ZIP
Execution Date: June 3, 2005	Additional name(s) & address(es) attached?YesX No
4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is	
A. Patent Application No.(s)	B. Patent No.(s)
11/105,701 filed April 13, 2005	
Additional numbers attached? Yes X No	1
Name and address of party to whom correspondence	6. Total number of applications and patents involved: 1
concerning document should be mailed:	
Name:Jay H. Maioli Internal Address:Cooper & Dunham LLP	7. Total fee (37 CFR 3.41):\$ 40.00
	X Enclosed Authorized to be charged to deposit account
Street Address: 1185 Avenue of the Americas	8. Deposit account number:
City: New York State: New York ZIP 10036	
DO NOT USE THIS SPACE	
9. Statement and signature.	
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Jay H. Maioli, Reg. No.27,213 June 23, 2005 Name of Person Signing Signature Date	
"	Total Number of many accomplished
Total Number of pages comprising cover sheet: 1 OMB No. 0651-0011 (exp. 4/94)	
Do not detach this portion Mail documents to be recorded with required cover sheet information to: Commissioner of Patents and Trademarks P.O. Box 1450 Alexandria, VA 2231-1450	
Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded, including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, D.C. 20231, and to the office of Management and Budget, Paperwork Reduction Project. (0651-0011). Washington, D.C. 20503	

06/28/2005 YPDLITE1 00000045 11195701

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PATENT REEL: 016736 FRAME: 0088

ASSTONMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in BINAURAL SOUND REPRODUCTION APPARATUS AND METHOD, AND RECORDING MEDIUM for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 6-7-35 Kitashinagawa, Shinagawa-Ku, Tokyo, Japan(hereinafter referenced as ASSIGNEE) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number $\underline{11/105,701}$, Filing Date $\underline{\text{April }13,\ 2005}$

PATENT REEL: 016736 FRAME: 0089 This assignment executed on the dates indicated below.

Kenji Nakano

Name of first or sole inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Kenji Nakano
Signature of first or sole inventor

Tune 3, 2005

Date of this assignment

RECORDED: 06/27/2005

PATENT REEL: 016736 FRAME: 0090